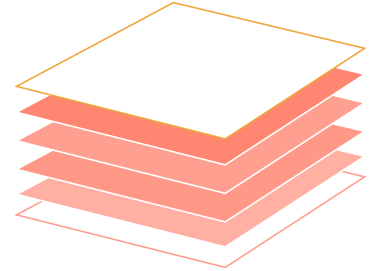


SinarVanda Hi-Brite GI, hite back folding box board (GC1) with high bulk and high brightness to deliver a light weight packaging solution. It is designed to serve both food and non-food packaging applications by combining properties to provide a higher yield, strength, and appearance as well as high quality printing and excellent color reproduction.

DOUBLE COATING	Min 20 gsm	Blade
TOP LAYER		NBKP + LBKP
UNDER LAYER		BCTMP
FILLER LAYER		BCTMP
BACK LAYER		NBKP + LBKP
COATING	Min 6 gsm	



### PRODUCT SPECIFICATION

GRAMMAGE T 410 om-02		CALIPER ISO 534:1988 (E)		STIFFNESS 15° T 556 om-05	
(g/m <sup>2</sup> )	(24" x 36" 500) lb	(µm)	(pt)	CD (mNm)	MD (mNm)
210 ± 3%	129 ± 3%	305 ± 3%	12.0 ± 3%	3.9	7.8
*) 215 ± 3%	132 ± 3%	320 ± 3%	12.6 ± 3%	4.1	8.5
230 ± 3%	141 ± 3%	350 ± 3%	13.8 ± 3%	5.4	11.3
245 ± 3%	151 ± 3%	380 ± 3%	15.0 ± 3%	7.3	13.9
260 ± 3%	160 ± 3%	410 ± 3%	16.1 ± 3%	8.3	16.4
280 ± 3%	172 ± 3%	450 ± 3%	17.7 ± 3%	10.3	20.5
305 ± 3%	187 ± 3%	500 ± 3%	19.7 ± 3%	13.1	25.7
330 ± 3%	203 ± 3%	550 ± 3%	21.7 ± 3%	15.6	30.8
360 ± 3%	221 ± 3%	600 ± 3%	23.6 ± 3%	20.0	35.0

\*) upon MoQ 200 ton

Tolerance for stiffness 15%

PROPERTY	UNIT	METHOD	SIDE	VALUES
Moisture Content	%	T 412 om-02		6.0 ± 1.0
Roughness	µm	T 555 om-04	TOP	1.10 ± 0.4
Brightness (D65/10°)	%	ISO 2470-2:2008 (E)	TOP	92.0 ± 2.0
Gloss 75°	%	T 480 om-05	TOP	Min 50.0
Internal Bond Strength	J/m <sup>2</sup>	T 569 pm-00		Min 130
Water Absorption COBB (60s)	g/m <sup>2</sup>	T 441 om-04	TOP	40 ± 15

### SHEETING PROCESS

Size Deviation	mm	ASTM D5625	0 - + 2.0
SQUARENESS	mm	ASTM D5625	Max 1.0

\*) Testing is done when production finished at room condition, Temp (°C) : 23 ± 1 and RH (%) : 50 ± 2

\*) Using reference TAPPI T 537 for counting dirt count in paper and paperboard

### APPLICATION USES

- Cosmetics, Toiletries, Detergents, Textile, Tools, Household Appliances.

Note :

- For first time customer/new application, please conduct plant trial first before commercial order.

- Strongly recommend to seek further technical advice and support from glue and ink vendors in terms of the board's adhesives compatibility and the board's printability/printing method respectively.

### RECOMMENDED PRINTING METHODS

- Offset

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All parameter measured to 95% confidence level

